HM5116400 Series — HITACHI/ LOGIC/ARRAYS/MEM

4,194,304-word × 4-bit Dynamic Random Access Memory

The Hitachi HM5116400 is a CMOS dynamic RAM organized 4,194,304 words × 4 bits. It employs the most advanced CMOS technology for high performance and low power. The HM5116400 offers Fast Page Mode as a high speed access mode.

Feature

- Single 5 V (±10%)
- High speed
  - Access time
    60 ns/ 70 ns/ 80 ns (max)
- Low power dissipation
  - Active mode
    440 mW/385 mW/358 mW (max)
  - Standby mode 11 mW (max)
- Fast page mode capability
- Long refresh period
  - 4096 refresh cycles : 64 ms
- 3 variations of refresh
  - $\overline{\text{RAS}}$-only refresh
  - $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh
  - Hidden refresh
- Test function
  - 16-bit parallel test mode

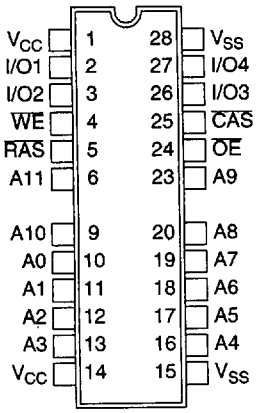
Ordering Information

Type No.	Access time	Package
HM5116400J-6	60 ns	400-mil 24/28-pin plastic SOJ (CP-24DA)
HM5116400J-7	70 ns	
HM5116400J-8	80 ns	
HM5116400Z-6	60 ns	475-mil 24-pin plastic ZIP (ZP-24A)
HM5116400Z-7	70 ns	
HM5116400Z-8	80 ns	
HM5116400TT-6	60 ns	24/28-pin plastic TSOP II (TTP-24D)
HM5116400TT-7	70 ns	
HM5116400TT-8	80 ns	
HM5116400RR-6	60 ns	
HM5116400RR-7	70 ns	
HM5116400RR-8	80 ns	

Note: This specification is fully compatible with the 16-Mbit DRAM specifications from TEXAS INSTRUMENTS.

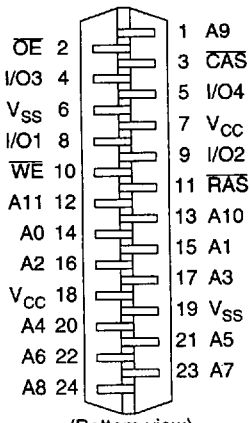
Pin Arrangement

HM5116400J Series



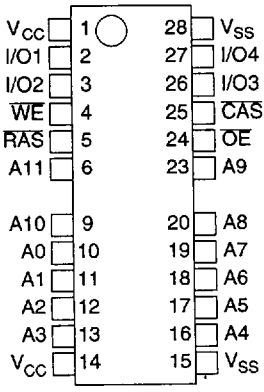
(Top view)

HM5116400Z Series



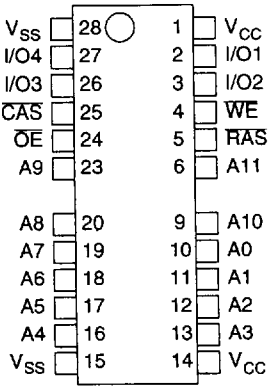
(Bottom view)

HM5116400TT Series



(Top view)

HM5116400RR Series



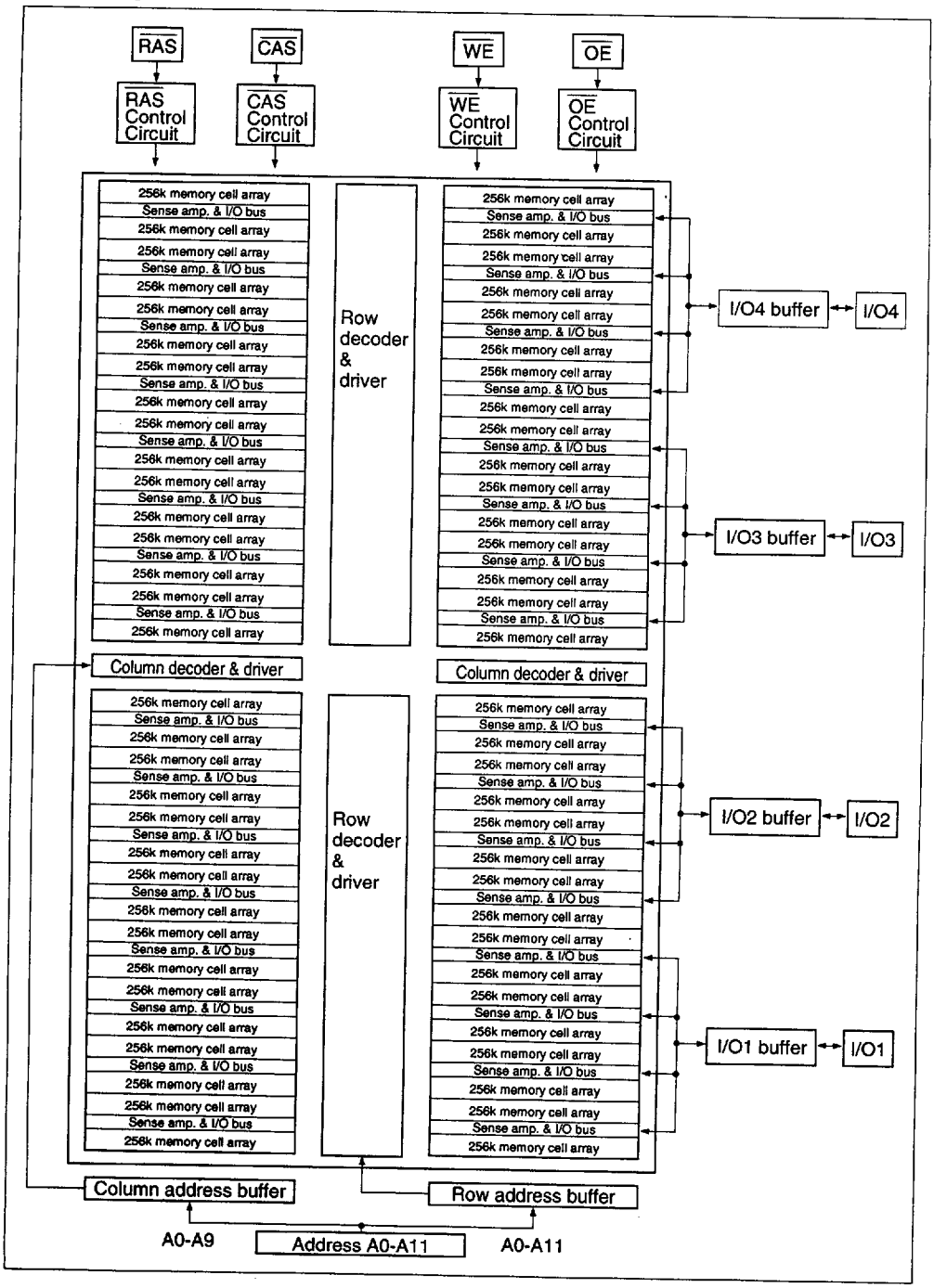
(Top view)

Pin Description

Pin name	Function
A0 to A11	Address input
A0 to A11	Refresh address input
I/O1 to I/O4	Data input/data output
$\overline{RAS}$	Row address strobe
$\overline{CAS}$	Column address strobe

Pin name	Function
$\overline{WE}$	Write enable
$\overline{OE}$	Output enable
V_{CC}	Power supply (+5 V)
V_{SS}	Ground
NC	No connection

Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	−1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	−1.0 to +7.0	V
Short circuit output current	Iout	50	mA
Power dissipation	P_T	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	−55 to +125	°C

Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V_{CC}	4.5	5.0	5.5	V	1
Input high voltage	V_{IH}	2.4	—	6.5	V	1
Input low voltage	V_{IL}	−1.0	—	0.8	V	1

Note : 1. All voltage referenced to V_{SS}

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V)

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Test condition	Notes
Operating current	I_{CC1}	—	80	—	70	—	65	mA	t_{RC} = min	1, 2
Standby current	I_{CC2}	—	2	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z	
		—	1	—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2V Dout = High-Z	
$\overline{RAS}$-only refresh current	I_{CC3}	—	80	—	70	—	65	mA	t_{RC} = min	2
Standby current	I_{CC5}	—	5	—	5	—	5	mA	$\overline{RAS}$ = V_{IH}, $\overline{CAS}$ = V_{IL} Dout = enable	1
$\overline{CAS}$-before-$\overline{RAS}$ refresh current	I_{CC6}	—	80	—	70	—	65	mA	t_{RC} = min	
Fast page mode current	I_{CC7}	—	90	—	80	—	75	mA	t_{PC} = min	1,3
Input leakage current	I_{LI}	–10	10	–10	10	–10	10	µA	0 V ≤ Vin ≤ 7 V	
Output leakage current	I_{LO}	–10	10	–10	10	–10	10	µA	0 V ≤ Vout ≤ 7 V Dout = disable	
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –5 mA	
Output low voltage	V_{OL}	0	0.4	0	0.4	0	0.4	V	Low Iout = 4.2 mA	

Notes : 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.
2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Address can be changed once or less while $\overline{CAS}$ = V_{IH}.

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 10%)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-in, Data-out)	$C_{I/O}$	—	7	pF	1, 2

Notes : 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
2. $\overline{CAS}$ = V_{IH} to disable Dout.

AC Characteristics ($Ta = 0$ to $+70°C$, $V_{CC} = 5\ V \pm 10\%$, $V_{SS} = 0\ V$) *1, *2, *3, *19, *20

Test Conditions

Input rise and fall times : 5 ns
Input timing reference levels : 0.8 V, 2.4 V
Output load : 2 TTL gate + C_L (100 pF)
(Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common parameters)

Parameter	Symbol	HM5116400 -6		HM5116400 -7		HM5116400 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	110	—	130	–	150	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	40	—	50	—	60	—	ns	
$\overline{CAS}$ precharge time	t_{CP}	10	—	10	—	10	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10000	70	10000	80	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	15	10000	18	10000	20	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	10	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	15	—	15	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	45	20	52	20	60	ns	4
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	15	40	ns	5
$\overline{RAS}$ hold time	t_{RSH}	15	—	18	—	20	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	60	—	70	—	80	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	5	—	5	—	5	—	ns	
$\overline{OE}$ to Din delay time	t_{OED}	15	—	18	—	20	—	ns	6
$\overline{OE}$ delay time from Din	t_{DZO}	0	—	0	—	0	—	ns	7
$\overline{CAS}$ delay time from Din	t_{DZC}	0	—	0	—	0	—	ns	7
Transition time (rise and fall)	t_T	3	30	3	30	3		ns	8

Read cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Access time from $\overline{RAS}$	t_{RAC}	—	60	—	70	—	80	ns	9, 10, 21
Access time from $\overline{CAS}$	t_{CAC}	—	15	—	18	—	20	ns	10, 11, 18, 21
Access time from address	t_{AA}	—	30	—	35	—	40	ns	10, 12 18, 21
Access time from $\overline{OE}$	t_{OEA}	—	15	—	18	—	20	ns	10, 21
Read command setup time	t_{RCS}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{CAS}$	t_{RCH}	0	—	0	—	0	—	ns	13
Read command hold time to $\overline{RAS}$	t_{RRH}	5	—	5	—	5	—	ns	13
Column address to $\overline{RAS}$ lead time	t_{RAL}	30	—	35	—	40	—	ns	
Column address to $\overline{CAS}$ lead time	t_{CAL}	30	—	35	—	40	—	ns	
$\overline{CAS}$ to output in low-Z	t_{CLZ}	0	—	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	3	—	ns	
Output data hold time from $\overline{OE}$	t_{OHO}	3	—	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	15	—	18	—	20	ns	14
Output buffer turn-off time to $\overline{OE}$	t_{OEZ}	—	15	—	18	—	20	ns	14
$\overline{CAS}$ to Din delay time	t_{CDD}	15	—	18	—	20		ns	6

Write cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Write command setup time	t_{WCS}	0	—	0	—	0	—	ns	15
Write command hold time	t_{WCH}	15	—	15	—	15	—	ns	
Write command pulse width	t_{WP}	15	—	15	—	15	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	15	—	18	—	20	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	15	—	18	—	20	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	0	—	ns	16
Data-in hold time	t_{DH}	15	—	15	—	15	—	ns	16

Read-modify-write cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Read-modify-write cycle time	t_{RWC}	155	—	181	—	205	—	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	85	—	98	—	110	—	ns	15
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	40	—	46	—	50	—	ns	15
Column address to $\overline{WE}$ delay time	t_{AWD}	55	—	63	—	70	—	ns	15
$\overline{OE}$ hold time from $\overline{WE}$	t_{OEH}	15	—	18	—	20	—	ns	

Refresh cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
$\overline{CAS}$ setup time (CBR refresh cycle)	t_{CSR}	10	—	10	—	10	—	ns	
$\overline{CAS}$ hold time (CBR refresh cycle)	t_{CHR}	20	—	20	—	20	—	ns	
$\overline{WE}$ setup time (CBR refresh cycle)	t_{WRP}	10	—	10	—	10	—	ns	
$\overline{WE}$ hold time (CBR refresh cycle)	t_{WRH}	10	—	10	—	10	—	ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	t_{RPC}	0	—	0	—	0	—	ns	

Fast page mode cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Fast page mode cycle time	t_{PC}	40	—	45	—	50	—	ns	
Fast page mode $\overline{RAS}$ pulse width	t_{RASP}	—	100000	—	—	100000	—	ns	17
Access time from $\overline{CAS}$ precharge	t_{CPA}	—	35	—	40	—	45	ns	10, 18, 21
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{CPRH}	35	—	40	—	45	—	ns	

Fast page mode read modify write cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Fast page mode read-modify-write cycle time	t_{PRWC}	85	—	96	—	105	—	ns	
$\overline{WE}$ delay time from $\overline{CAS}$ precharge	t_{CPW}	60	—	68	—	75	—	ns	15

Test mode cycle *20

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
Test mode $\overline{WE}$ setup time	t_{WTS}	10	—	10	—	10	—	ns	
Test mode $\overline{WE}$ hold time	t_{WTH}	10	—	10	—	10	—	ns	

Counter test cycle

Parameter	Symbol	HM5116400 -6 Min	HM5116400 -6 Max	HM5116400 -7 Min	HM5116400 -7 Max	HM5116400 -8 Min	HM5116400 -8 Max	Unit	Notes
$\overline{CAS}$ precharge time in counter test cycle	t_{CPT}	40	—	40	—	40	—	ns	

Refresh

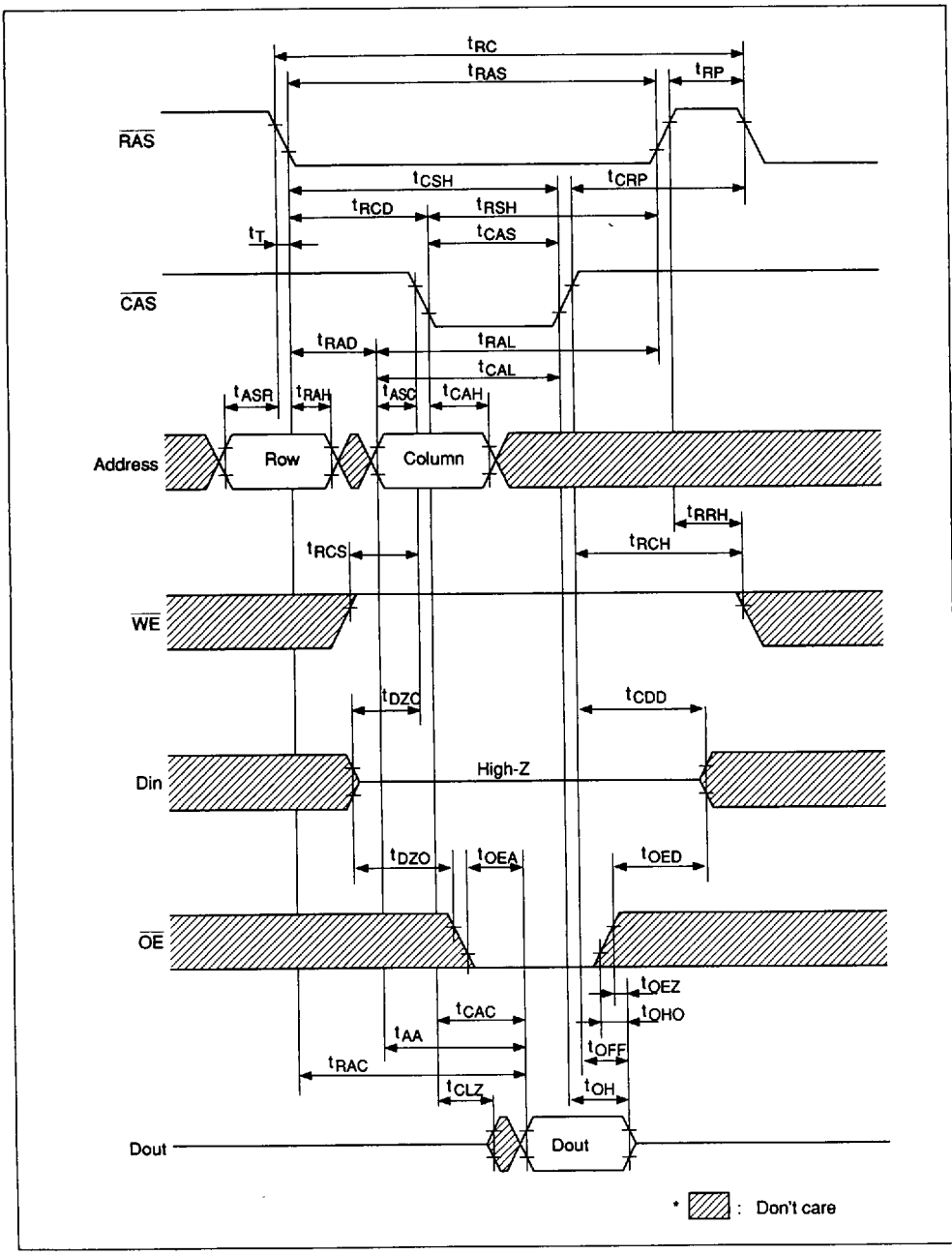
Parameter	Symbol	Max	Unit	Notes
Refresh period	t_{REF}	64	ms	4096 cycles

Notes:
1. AC measurements assume t_T = 5 ns.
2. An initial pause of 200 µs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing $\overline{RAS}$-only refresh or $\overline{CAS}$-before-$\overline{RAS}$ refresh). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$-before-$\overline{RAS}$ refresh cycles are required.
3. Only row address is indispensable on address A10 and A11.
4. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
5. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by tAA.
6. Either t_{OED} or t_{CDD} must be satisfied.
7. Either t_{DZO} or t_{DZC} must be satisfied.
8. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
9. Assume that $t_{RCD} < t_{RCD}$ (max) and $t_{RAD} < t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
10. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
11. Assume that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max).
12. Assume that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \geq t_{RAD}$(max).
13. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
14. t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referenced to output voltage levels.
15. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}$ (min), $t_{CWD} \geq t_{CWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), or $t_{CWD} \geq t_{CWD}$ (min), $t_{AWD} \geq t_{AWD}$ (min) and $t_{CPW} \geq t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
16. These parameters are referenced to $\overline{CAS}$ leading edge in early write cycles and to $\overline{WE}$ leading edge in delayed write or read-modify-write cycles.
17. t_{RASP} defines $\overline{RAS}$ pulse width in fast page mode cycles.
18. Access time is determined by the longer of t_{AA} or t_{CAC} or t_{CPA}.
19. In delayed write or read-modify-write cycles, $\overline{OE}$ must disable output buffer prior to applying data to the device. After $\overline{RAS}$ is reset, if $t_{OEH} \geq t_{CWL}$, the I/O pin will remain open circuit (high impedance); if $t_{OEH} < t_{CWL}$, invalid data will be out at each I/O.
20. The 16M DRAM offers a 16-bits time saving parallel test mode. Address CA0 and CA1 for the 4M × 4 are don't care during test mode. Test mode is set by performing a $\overline{WE}$-and-$\overline{CAS}$-before-$\overline{RAS}$ (WCBR) cycle. In 16-bits parallel test mode, data is written into 4 bits in parallel at each I/O (I/O1 to I/O4) and read out from each I/O.
    If 4 bits of each I/O are equal (all 1s or 0s), data output pin is a high state during test mode read cycle, then the device has passed. If they are not equal, data output pin is a low state, then the device has failed.
    Refresh during test mode operation can be performed by normal read cycles or by WCBR refresh cycles.
    To get out of test mode and enter a normal operation mode, perform either a regular $\overline{CAS}$-before-$\overline{RAS}$ refresh cycle or $\overline{RAS}$-only refresh cycle.

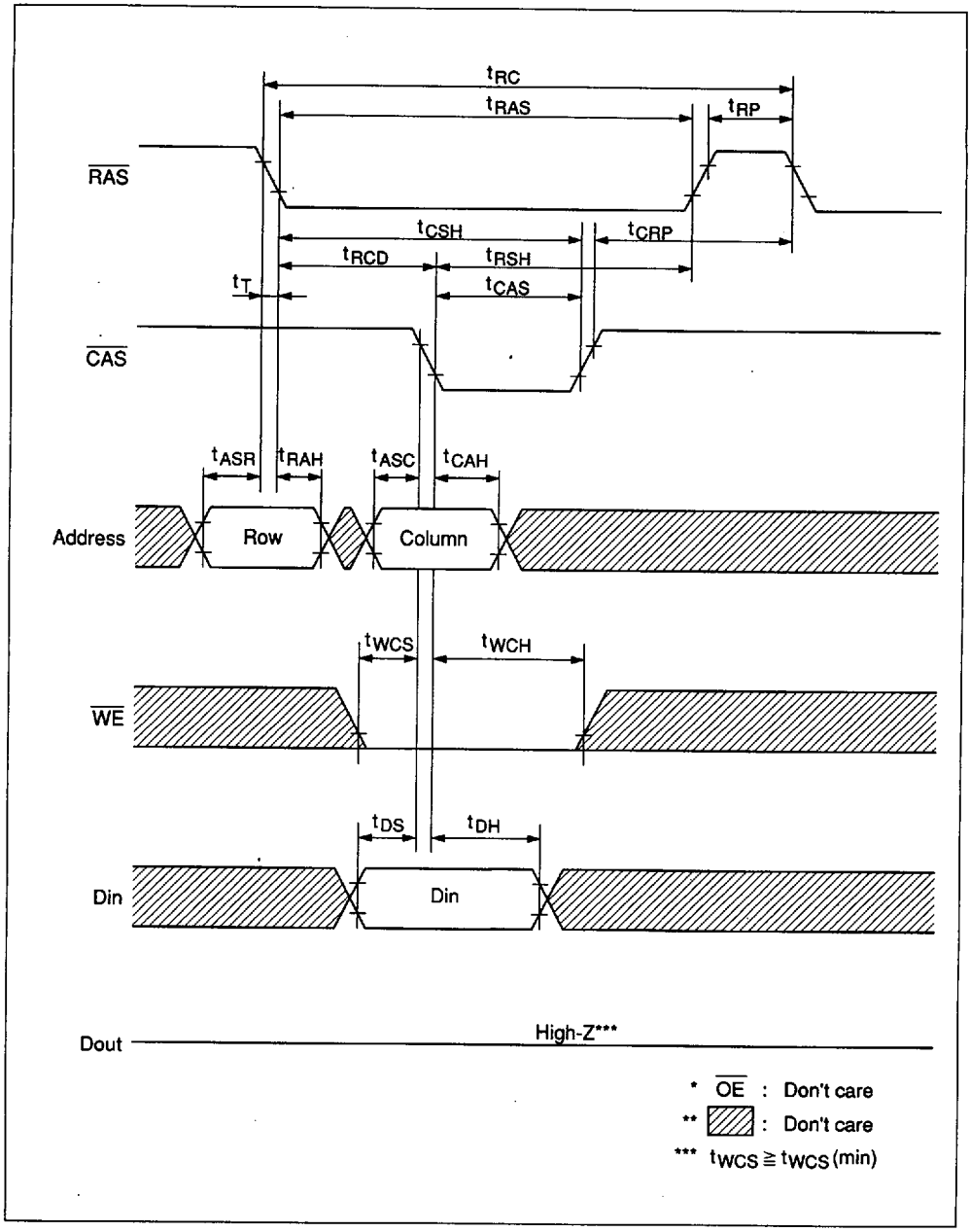
21. In a test mode read cycle, the value of t_{RAC}, t_{AA}, t_{CAC} and t_{CPA} is delayed by 2 ns to 5 ns for the specified value. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.

Timing Waveforms

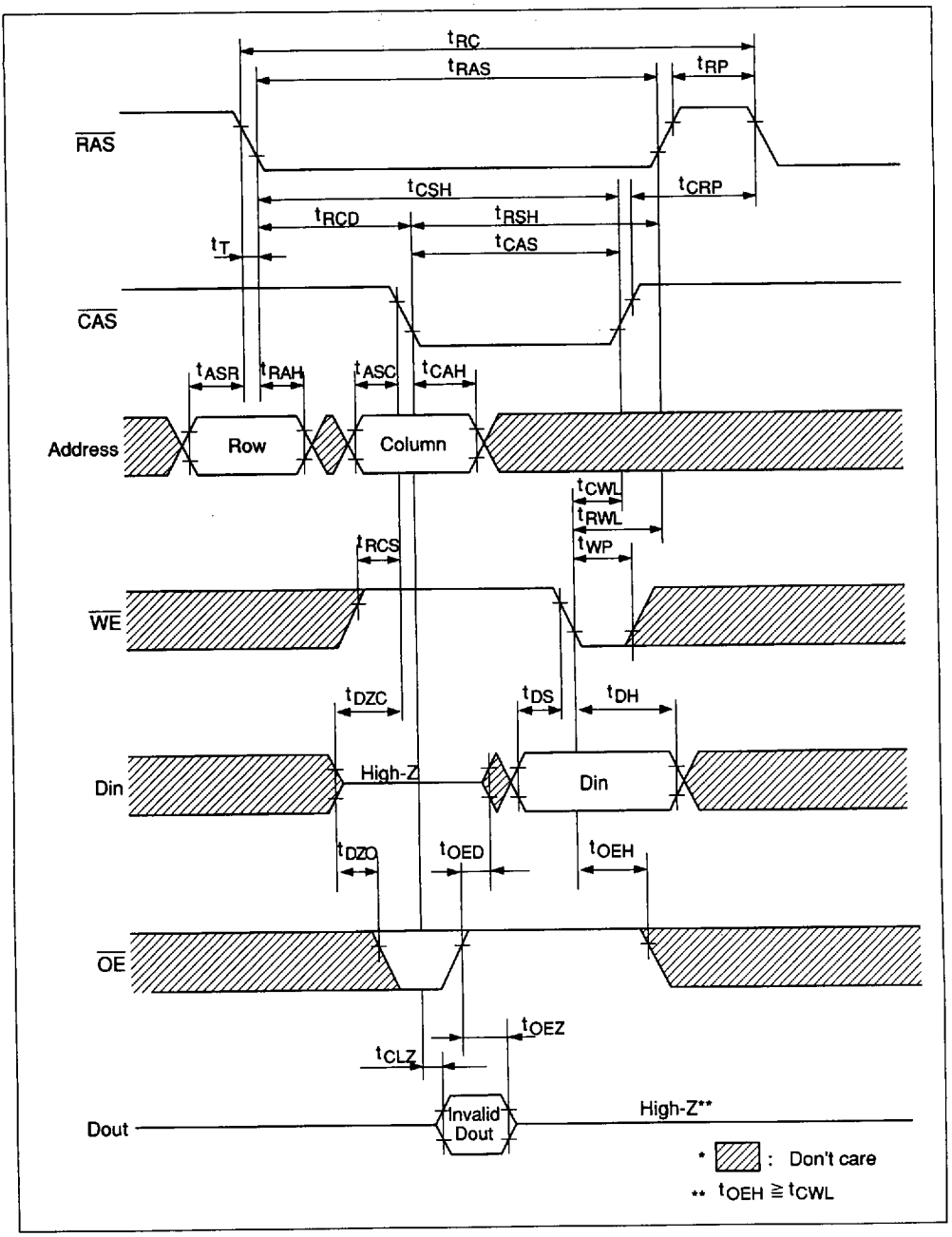
Read Cycle



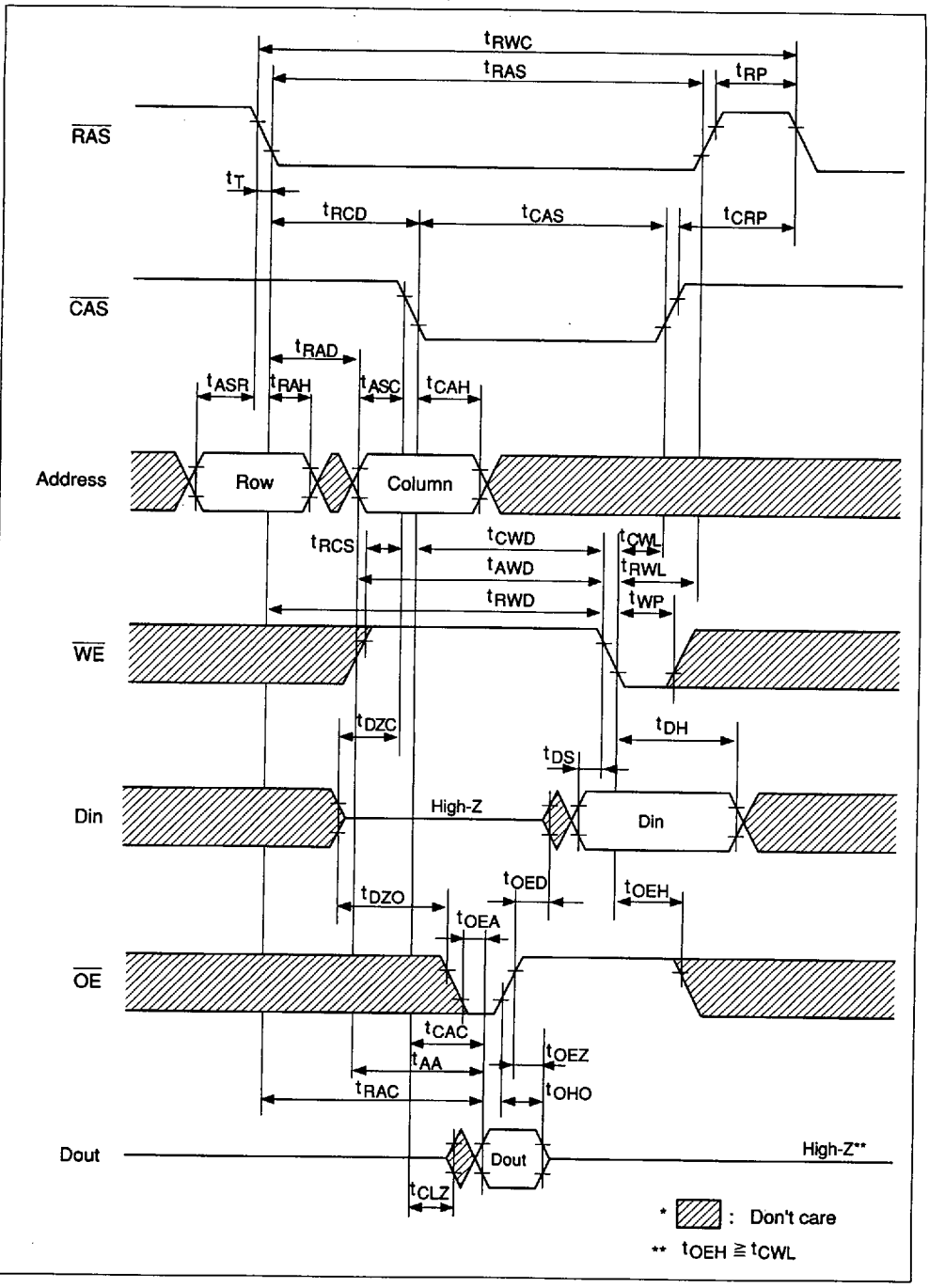
Early Write Cycle



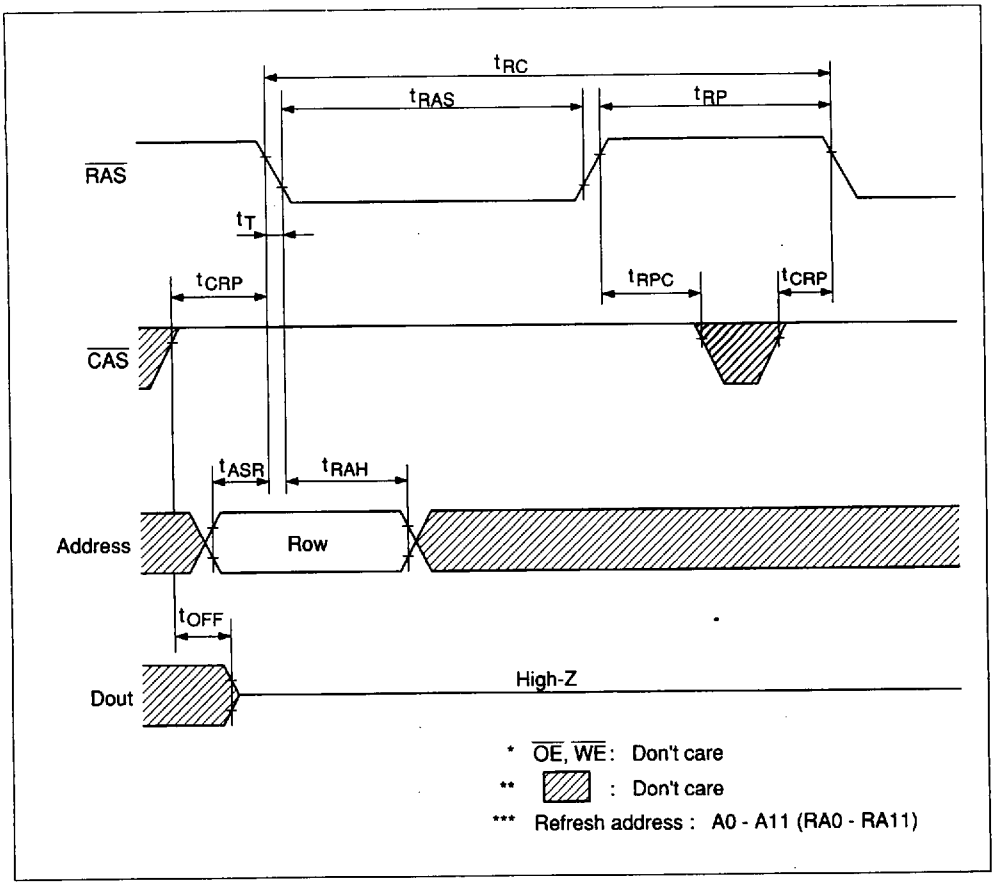
Delayed Write Cycle *19



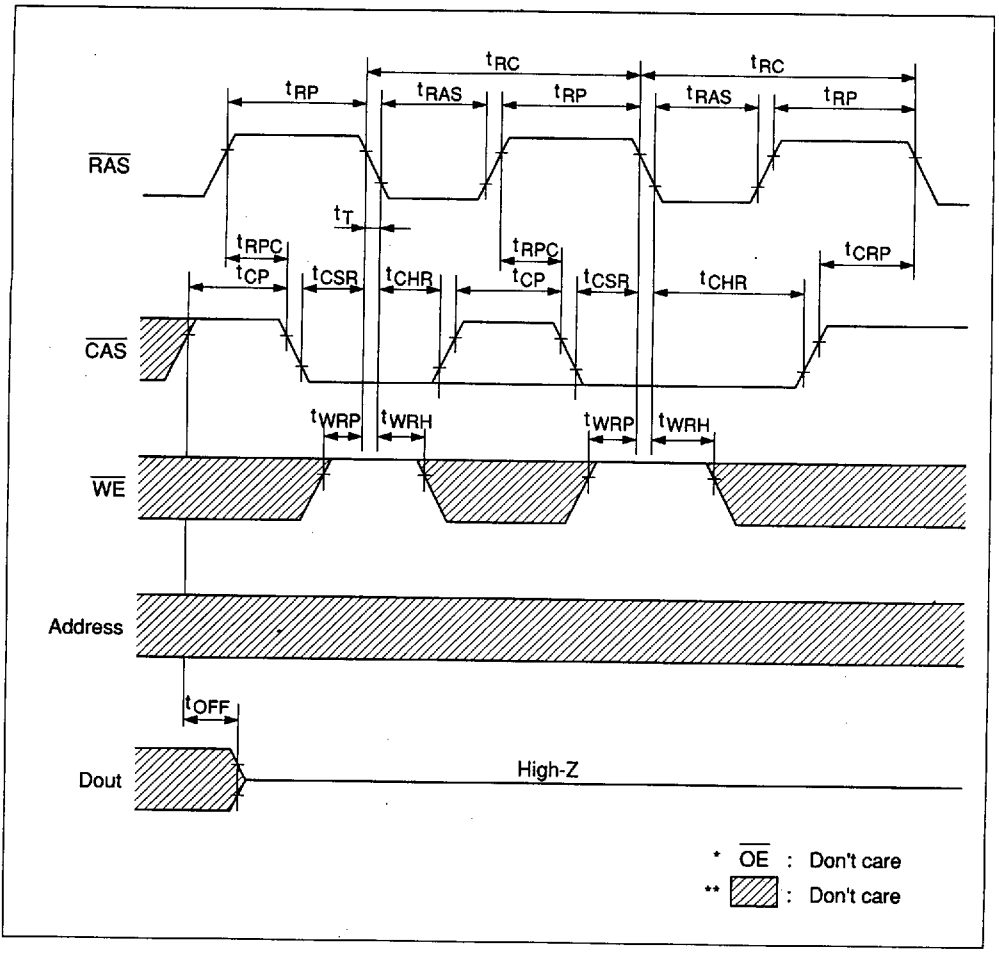
Read-Modify-Write Cycle *19



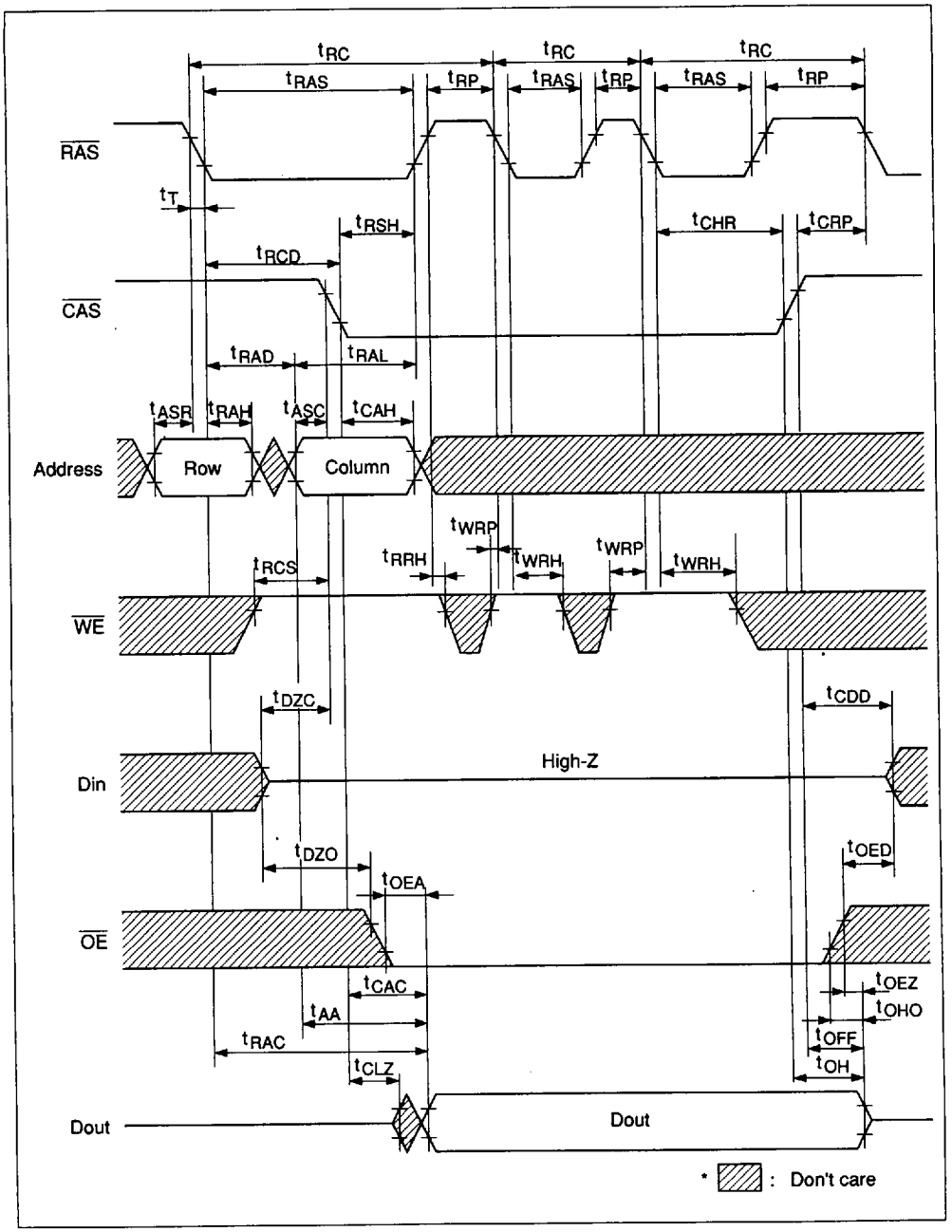
$\overline{RAS}$-Only Refresh Cycle



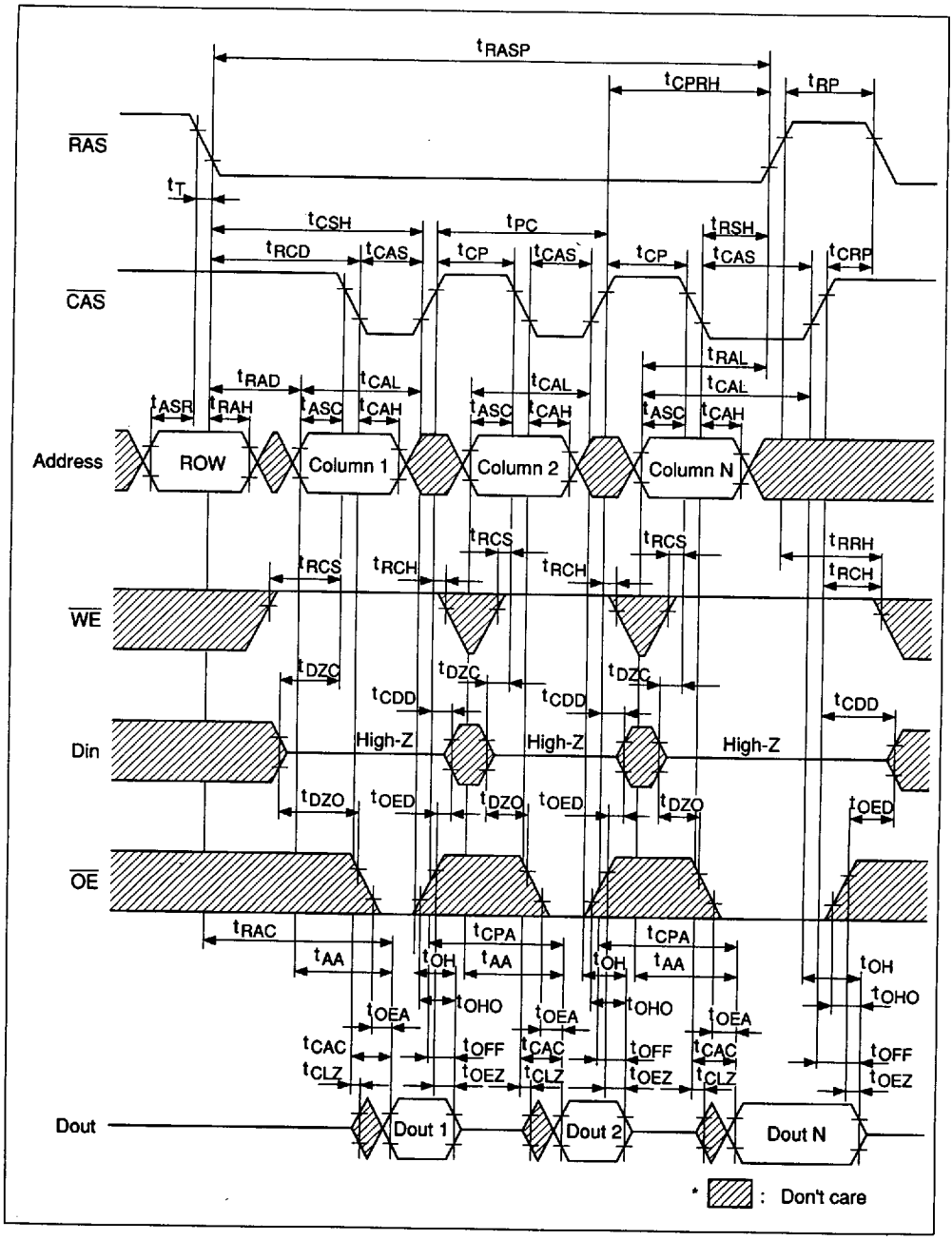
$\overline{CAS}$-Before-$\overline{RAS}$ Refresh Cycle



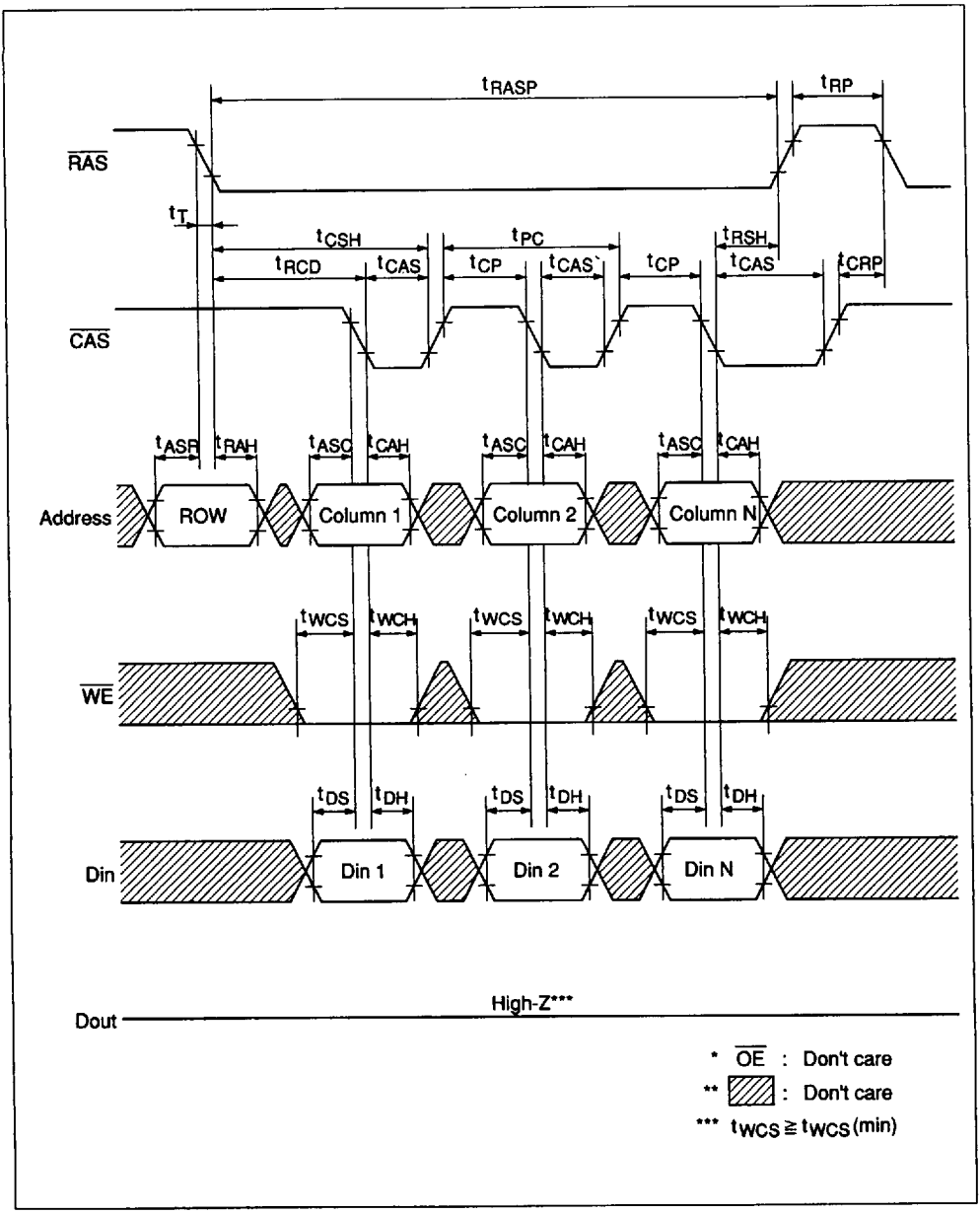
Hidden Refresh Cycle



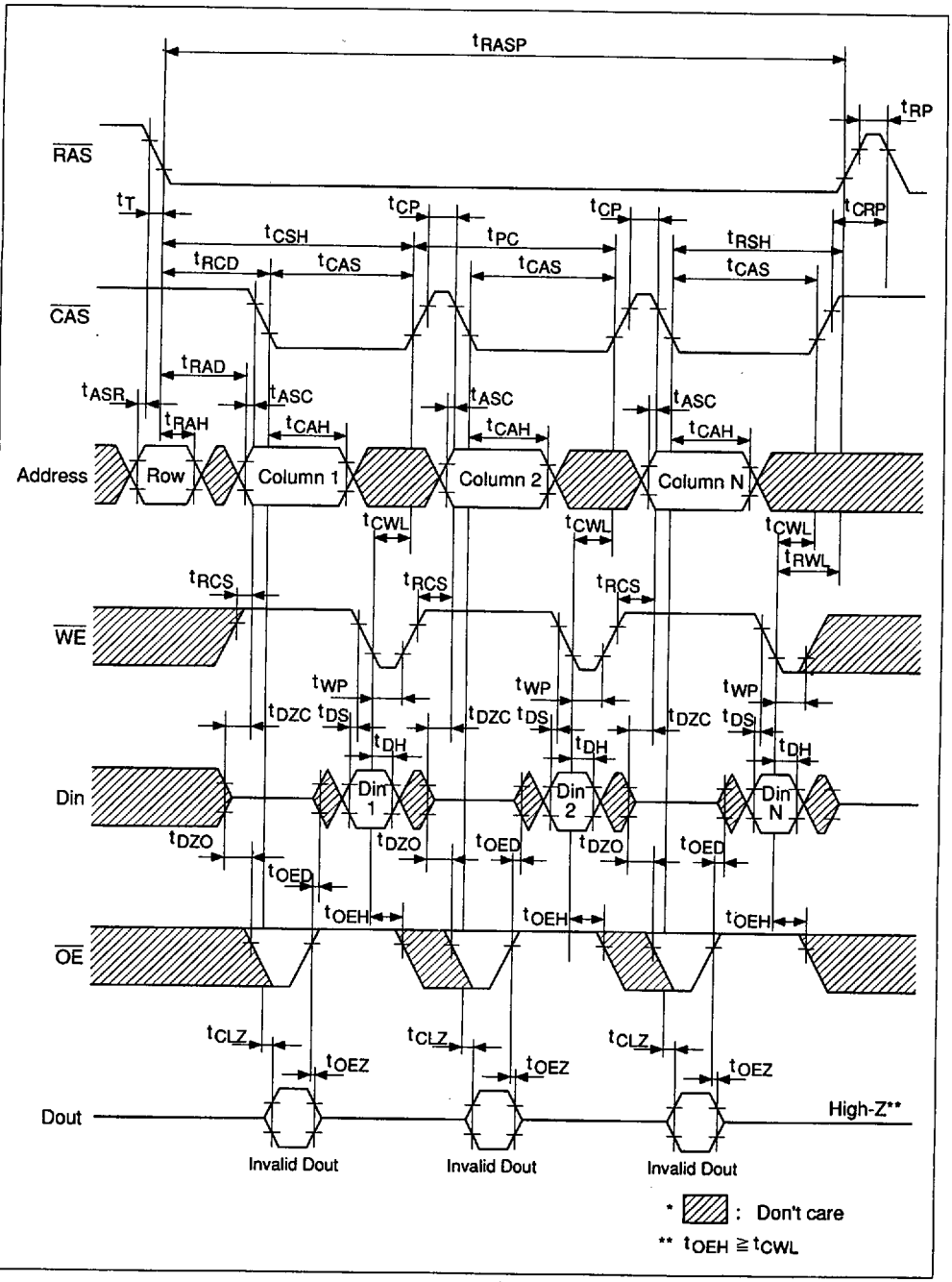
Fast Page Mode Read Cycle



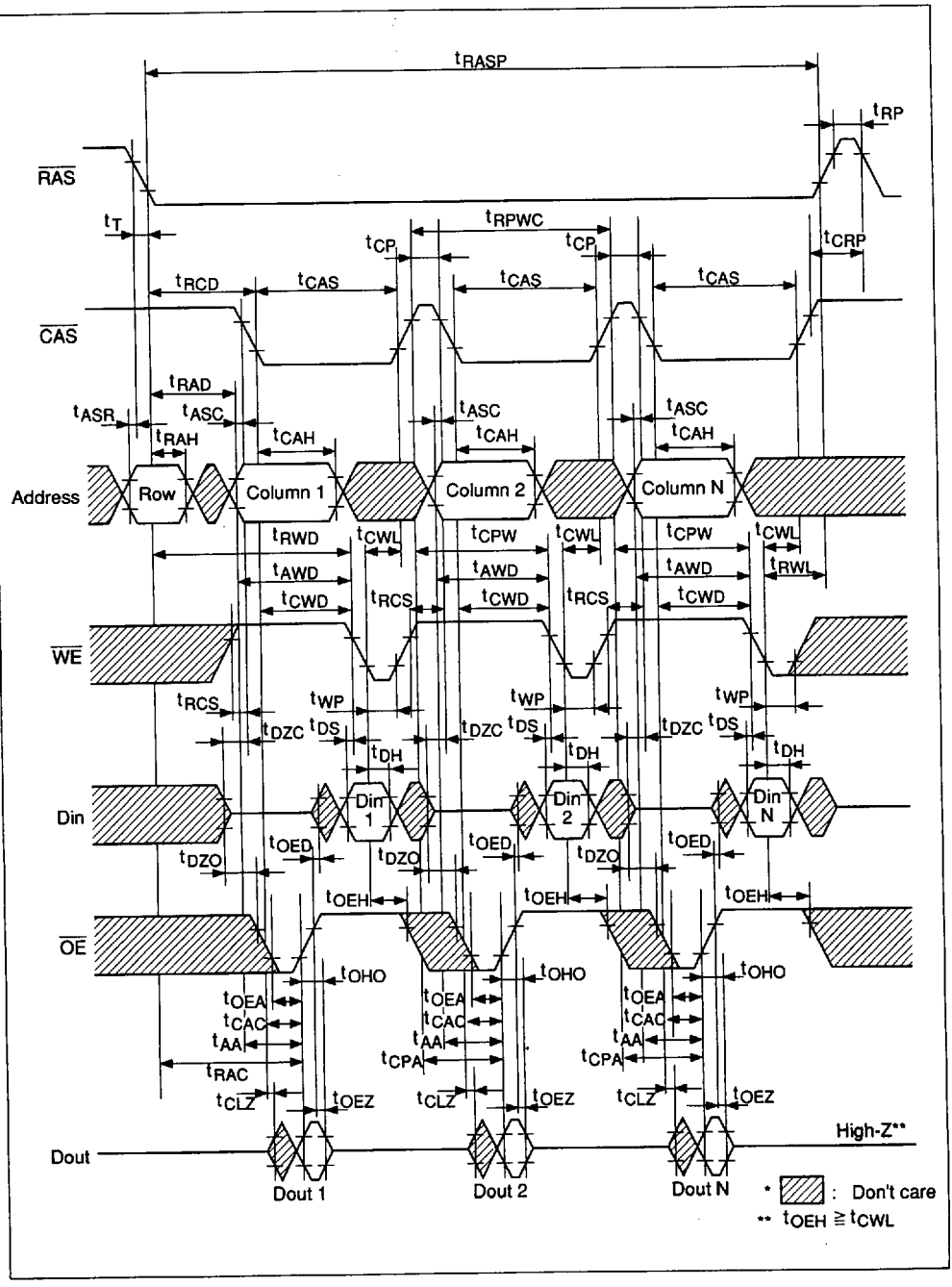
Fast Page Mode Early Write Cycle



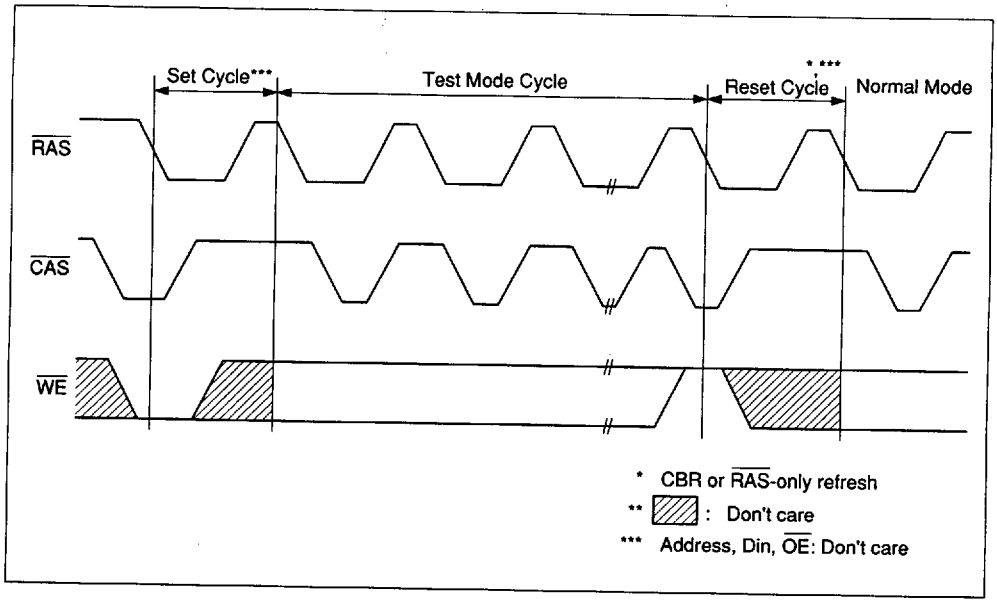
Fast Page Mode Delayed Write Cycle *19



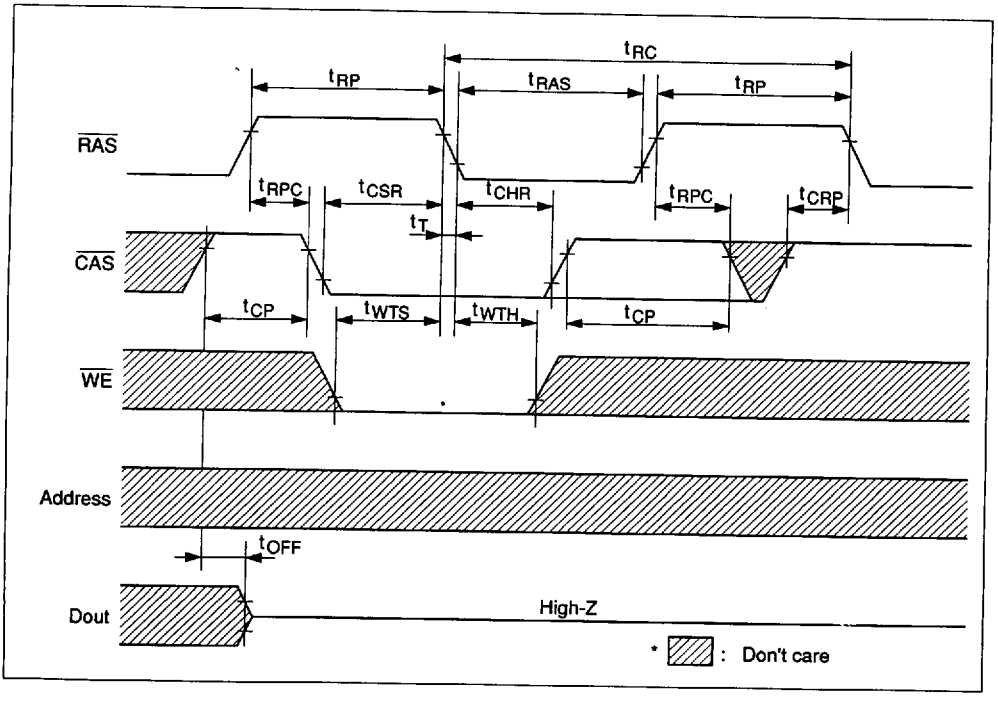
Fast Page Mode Read-Modify-Write Cycle *19



Test Mode Cycle *20

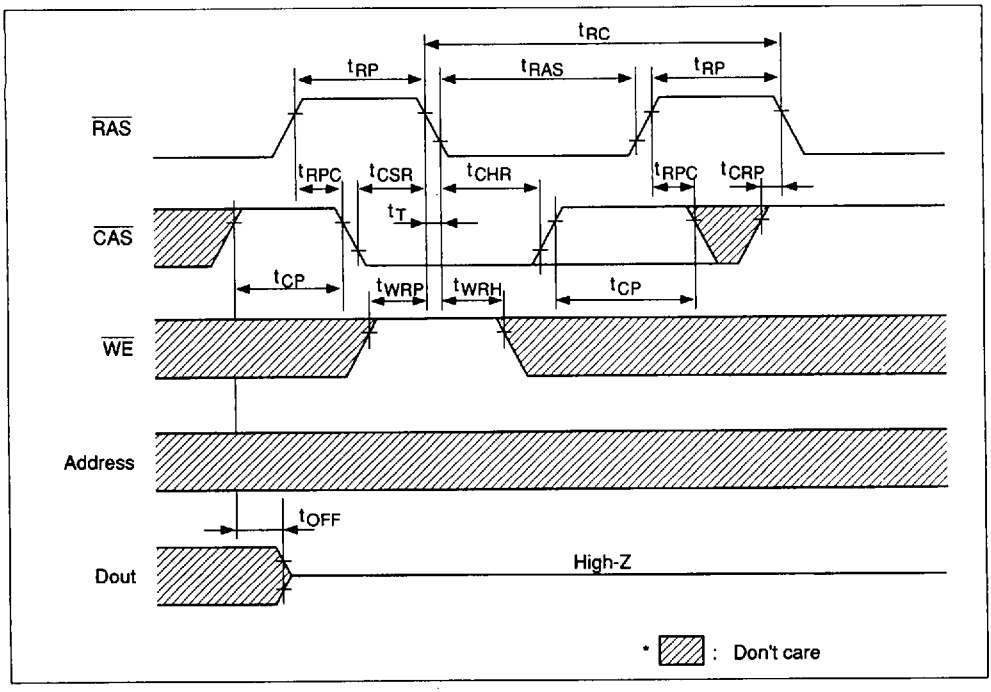


Test Mode Set Cycle

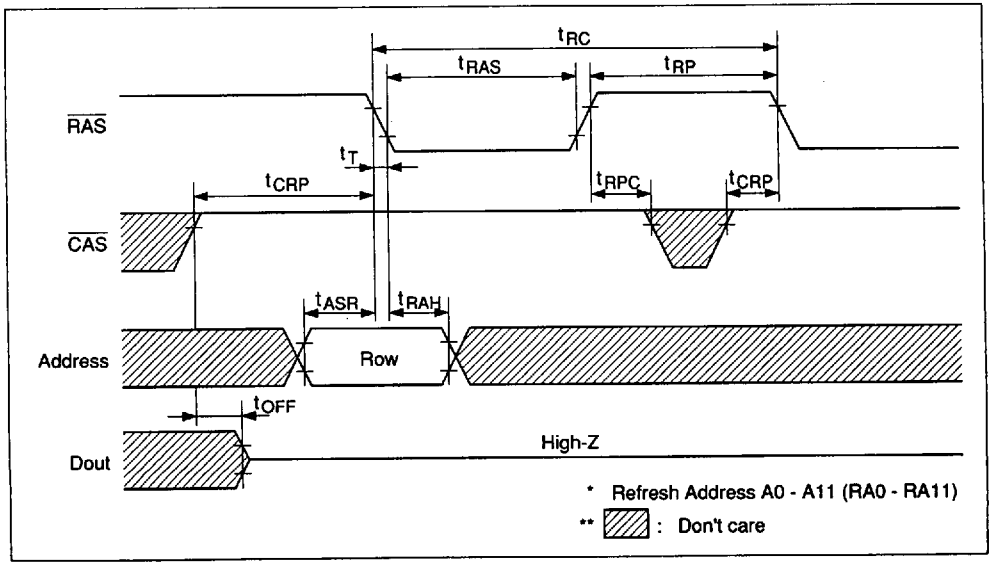


Test Mode Reset Cycle

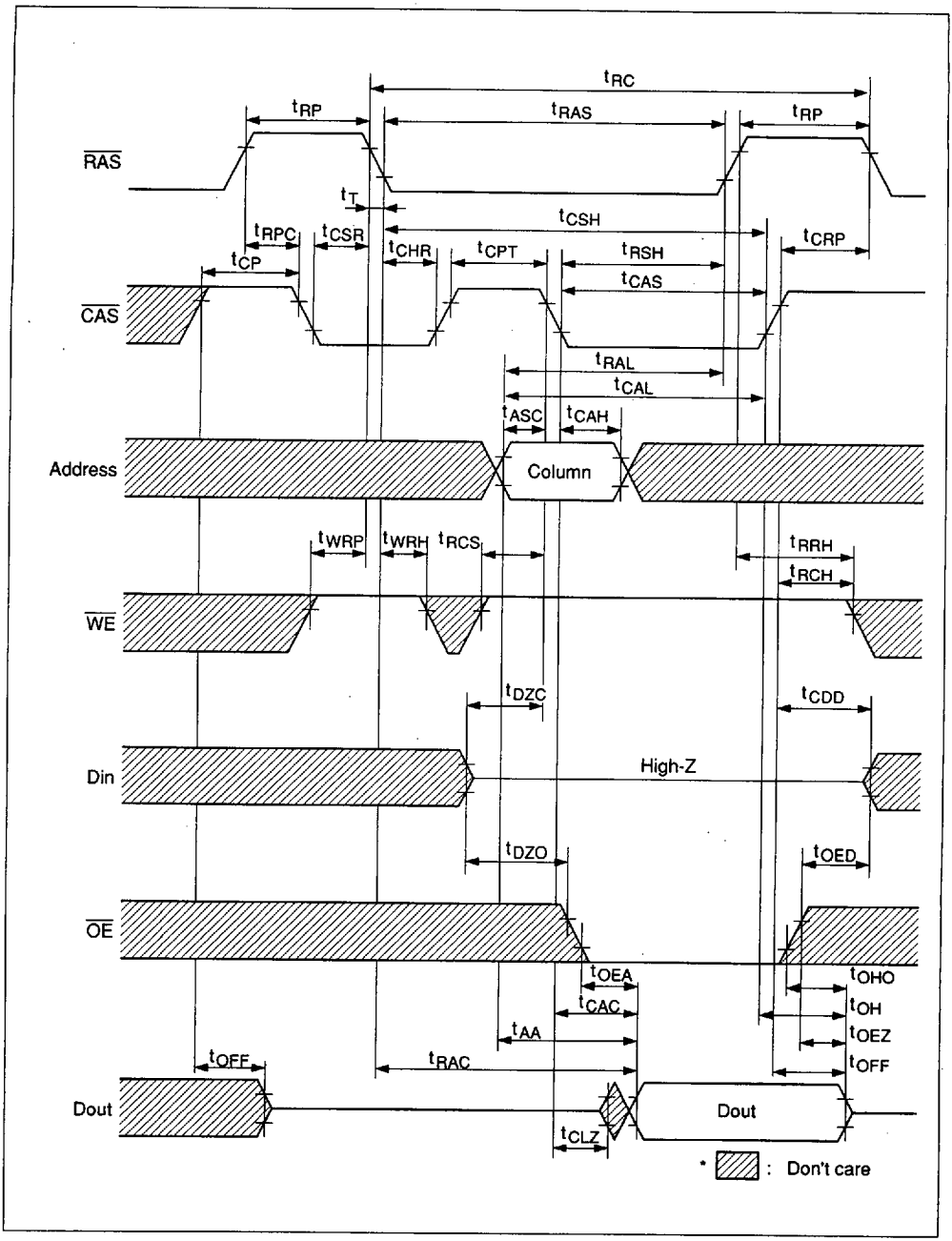
$\overline{CAS}$-Before-$\overline{RAS}$ Refresh Cycle



$\overline{RAS}$-Only Refresh Cycle



$\overline{CAS}$-Before-$\overline{RAS}$ Refresh Counter Check Cycle (Read)



$\overline{CAS}$-Before-$\overline{RAS}$ Refresh Counter Check Cycle (Write)